

TJK/182/L.W.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of Soon-Bin JUNG et al. ) HIGH DENSITY PLASMA PROCESSING  
Korean Appln. No. 2000-32869 ) APPARATUS  
Korean Filing Date: June 15, 2000 )

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

Please amend the subject application as follows:

**--CROSS REFERENCE TO RELATED APPLICATION**

This application claims the priority of Korean patent application Serial No. 2000-32869

filed on June 15, 2000.-

Respectfully submitted,

Date: 6/15/01  
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